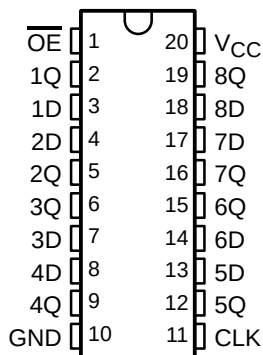


SN54AHC374, SN74AHC374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

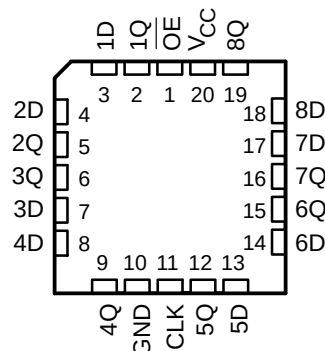
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- Operating Range 2-V to 5.5-V V_{CC}
- 3-State Outputs Drive Bus Lines Directly
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SN54AHC374 . . . J OR W PACKAGE
SN74AHC374 . . . DB, DGV, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHC374 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

The 'AHC374 devices are octal edge-triggered D-type flip-flops that feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels of the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AHC374N	SN74AHC374N
	SOIC – DW	Tube	SN74AHC374DW	AHC374
		Tape and reel	SN74AHC374DWR	
	SOP – NS	Tape and reel	SN74AHC374NSR	AHC374
	SSOP – DB	Tape and reel	SN74AHC374DBR	HA374
	TSSOP – PW	Tube	SN74AHC374PW	HA374
		Tape and reel	SN74AHC374PWR	
–55°C to 125°C	TVSOP – DGV	Tape and reel	SN74AHC374DGV	HA374
	CDIP – J	Tube	SNJ54AHC374J	SNJ54AHC374J
	CFP – W	Tube	SNJ54AHC374W	SNJ54AHC374W
	LCCC – FK	Tube	SNJ54AHC374FK	SNJ54AHC374FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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SN54AHC374, SN74AHC374
OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS
WITH 3-STATE OUTPUTS

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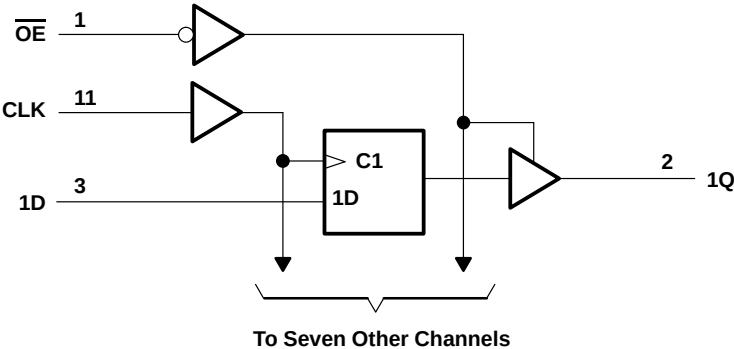
description/ordering information (continued)

$\overline{OE}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE (each flip-flop)			
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	$\uparrow$	H	H
L	$\uparrow$	L	L
L	H or L	X	Q_0
H	X	X	Z

logic diagram (positive logic)



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Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Output voltage range, V_O (see Note 1)	−0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	−20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±75 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	70°C/W
DGV package	92°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, T_{Stg}	−65°C to 150°C

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

			SN54AHC374		SN74AHC374		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2	5.5	2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5		V
		V _{CC} = 3 V	2.1		2.1		
		V _{CC} = 5.5 V	3.85		3.85		
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.5		0.5	V
		V _{CC} = 3 V		0.9		0.9	
		V _{CC} = 5.5 V		1.65		1.65	
V _I	Input voltage		0	5.5	0	5.5	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V		−50		−50	μA
		V _{CC} = 3.3 V ± 0.3 V		−4		−4	mA
		V _{CC} = 5 V ± 0.5 V		−8		−8	
I _{OL}	Low-level output current	V _{CC} = 2 V		50		50	μA
		V _{CC} = 3.3 V ± 0.3 V		4		4	mA
		V _{CC} = 5 V ± 0.5 V		8		8	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 3.3 V ± 0.3 V		100		100	ns/V
		V _{CC} = 5 V ± 0.5 V		20		20	
T _A	Operating free-air temperature		−55	125	−40	85	°C



SN54AHC374, SN74AHC374

OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHC374		SN74AHC374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 µA	2 V	1.9	2		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	I _{OH} = -4 mA	3 V	2.58			2.48		2.48		
	I _{OH} = -8 mA	4.5 V	3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 µA	2 V			0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1	
	I _{OL} = 4 mA	3 V			0.36		0.5		0.44	
	I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44	
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*		±1	µA
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.25		±2.5		±2.5	µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		40		40	µA
C _i	V _I = V _{CC} or GND	5 V		4	10				10	pF
C _o	V _O = V _{CC} or GND	5 V		6						pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		SN54AHC374		SN74AHC374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, CLK high or low	5		5.5		5.5		ns
t _{su}	Setup time, data before CLK↑	4.5		4		4		ns
t _h	Hold time, data after CLK↑	2		2		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		SN54AHC374		SN74AHC374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, CLK high or low	5		5		5		ns
t _{su}	Setup time, data before CLK↑	3		3		3		ns
t _h	Hold time, data after CLK↑	2		2		2		ns



SN54AHC374, SN74AHC374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHC374		SN74AHC374		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\max}$			$C_L = 15\text{ pF}$	80*	130*		70*		70		MHz
			$C_L = 50\text{ pF}$	55	85		50		50		
t_{PLH}	CLK	Q	$C_L = 15\text{ pF}$		8.1*	12.7*	1*	15*	1	15	ns
t_{PHL}					8.1*	12.7*	1*	15*	1	15	
t_{PZH}	$\overline{OE}$	Q	$C_L = 15\text{ pF}$		7.1*	11*	1*	13*	1	13	ns
t_{PZL}					7.1*	11*	1*	13*	1	13	
t_{PHZ}	$\overline{OE}$	Q	$C_L = 15\text{ pF}$		7.5*	10.5*	1*	12.5*	1	12.5	ns
t_{PLZ}					7.5*	10.5*	1*	12.5*	1	12.5	
t_{PLH}	CLK	Q	$C_L = 50\text{ pF}$		10.6	16.2	1	18.5	1	18.5	ns
t_{PHL}					10.6	16.2	1	18.5	1	18.5	
t_{PZH}	$\overline{OE}$	Q	$C_L = 50\text{ pF}$		9.6	14.5	1	16.5	1	16.5	ns
t_{PZL}					9.6	14.5	1	16.5	1	16.5	
t_{PHZ}	$\overline{OE}$	Q	$C_L = 50\text{ pF}$		10.2	14	1	16	1	16	ns
t_{PLZ}					10.2	14	1	16	1	16	
$t_{sk(0)}$			$C_L = 50\text{ pF}$			1.5**				1.5	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHC374		SN74AHC374		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\max}$			$C_L = 15\text{ pF}$	130*	185*		110*		110		MHz
			$C_L = 50\text{ pF}$	85	120		75		75		
t_{PLH}	CLK	Q	$C_L = 15\text{ pF}$		5.4*	8.1*	1*	9.5*	1	9.5	ns
t_{PHL}					5.4*	8.1*	1*	9.5*	1	9.5	
t_{PZH}	$\overline{OE}$	Q	$C_L = 15\text{ pF}$		5.1*	7.6*	1*	9*	1	9	ns
t_{PZL}					5.1*	7.6*	1*	9*	1	9	
t_{PHZ}	$\overline{OE}$	Q	$C_L = 15\text{ pF}$		4.6*	6.8*	1*	8*	1	8	ns
t_{PLZ}					4.6*	6.8*	1*	8*	1	8	
t_{PLH}	CLK	Q	$C_L = 50\text{ pF}$		6.9	10.1	1	11.5	1	11.5	ns
t_{PHL}					6.9	10.1	1	11.5	1	11.5	
t_{PZH}	$\overline{OE}$	Q	$C_L = 50\text{ pF}$		6.6	9.6	1	11	1	11	ns
t_{PZL}					6.6	9.6	1	11	1	11	
t_{PHZ}	$\overline{OE}$	Q	$C_L = 50\text{ pF}$		6.1	8.8	1	10	1	10	ns
t_{PLZ}					6.1	8.8	1	10	1	10	
$t_{sk(0)}$			$C_L = 50\text{ pF}$			1**				1	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.



SN54AHC374, SN74AHC374

OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

WITH 3-STATE OUTPUTS

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noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 4)

PARAMETER	SN74AHC374			UNIT
	MIN	TYP	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic V_{OL}		0.5	1	V
$V_{OL(V)}$ Quiet output, minimum dynamic V_{OL}		–0.5	–0.8	V
$V_{OH(V)}$ Quiet output, minimum dynamic V_{OH}		4		V
$V_{IH(D)}$ High-level dynamic input voltage		3.5		V
$V_{IL(D)}$ Low-level dynamic input voltage			1.5	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	32	pF

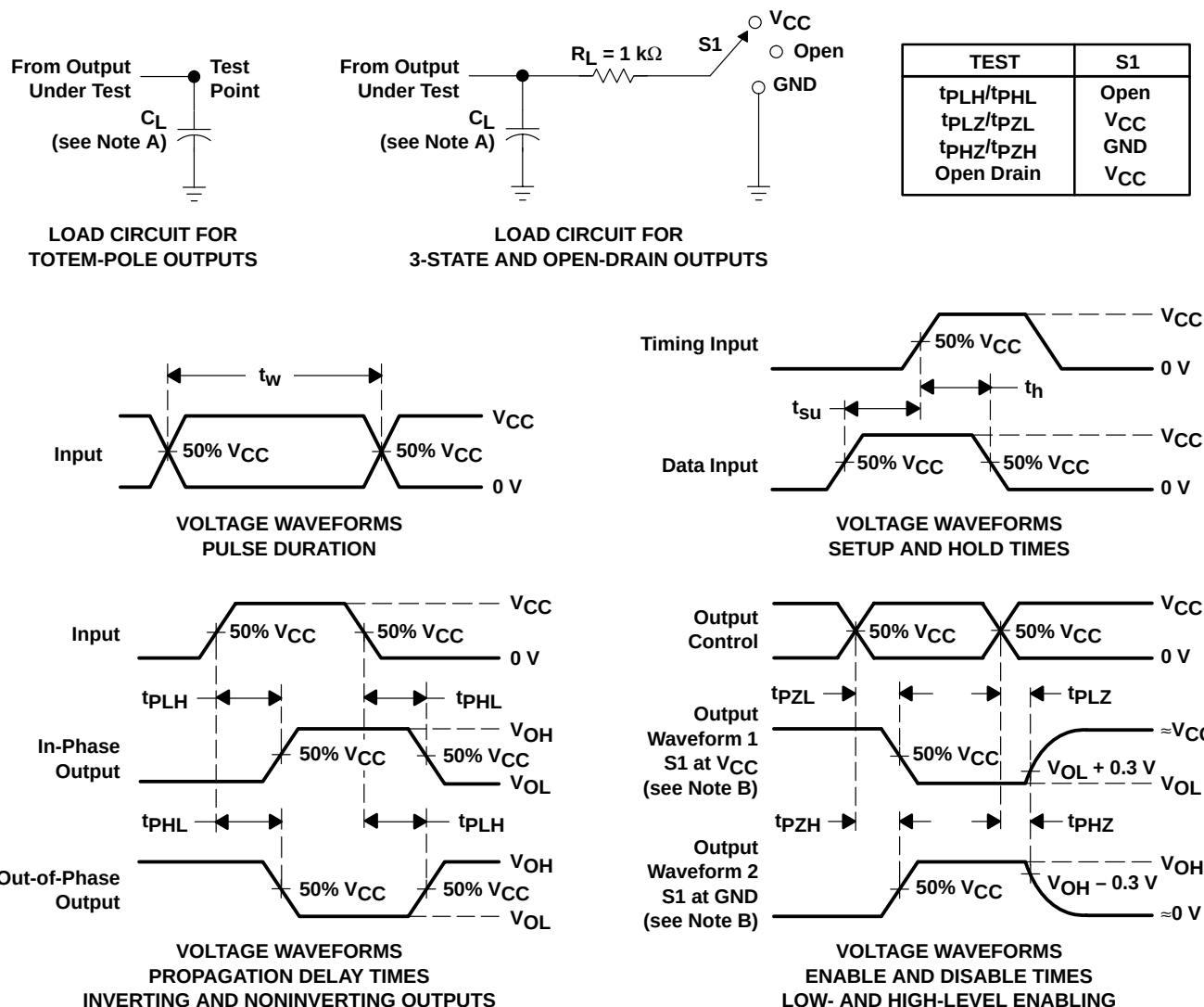


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SN54AHC374, SN74AHC374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9686401Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9686401QRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
5962-9686401QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SN74AHC374DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74AHC374DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DGVRE4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DGVRG4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHC374NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHC374NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74AHC374PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC374PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHC374PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54AHC374FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AHC374J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SNJ54AHC374W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

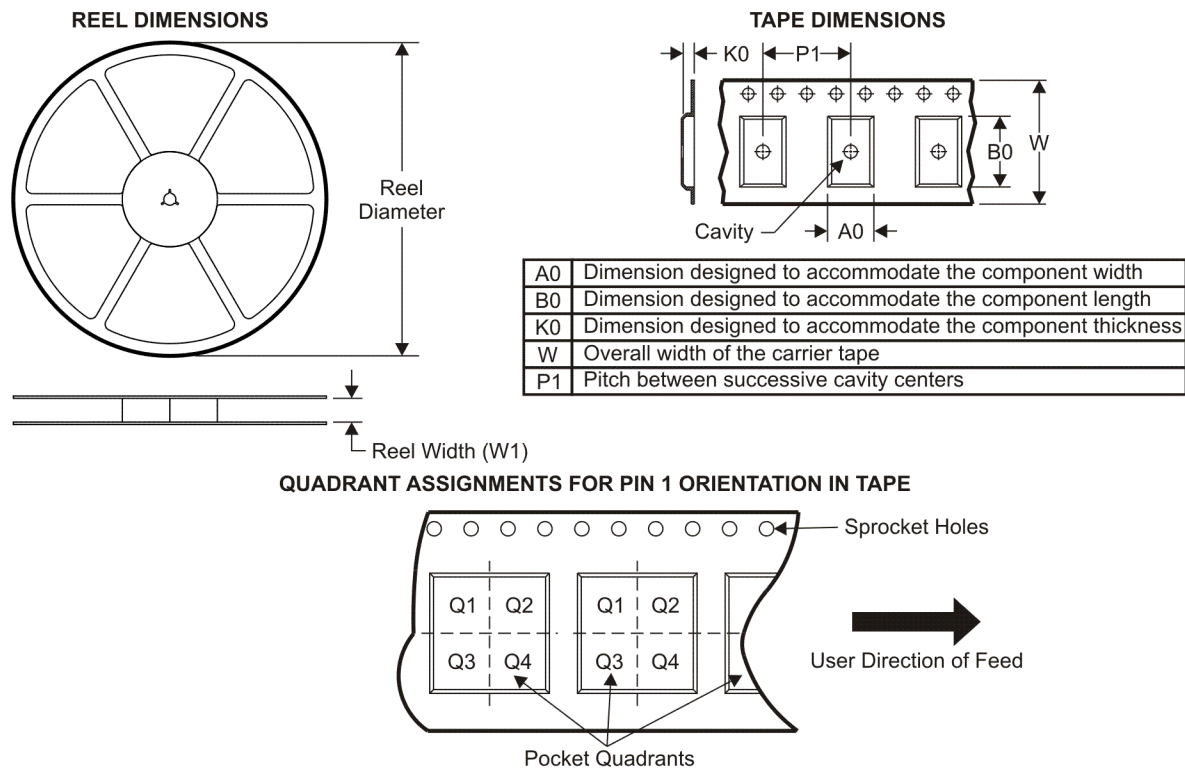
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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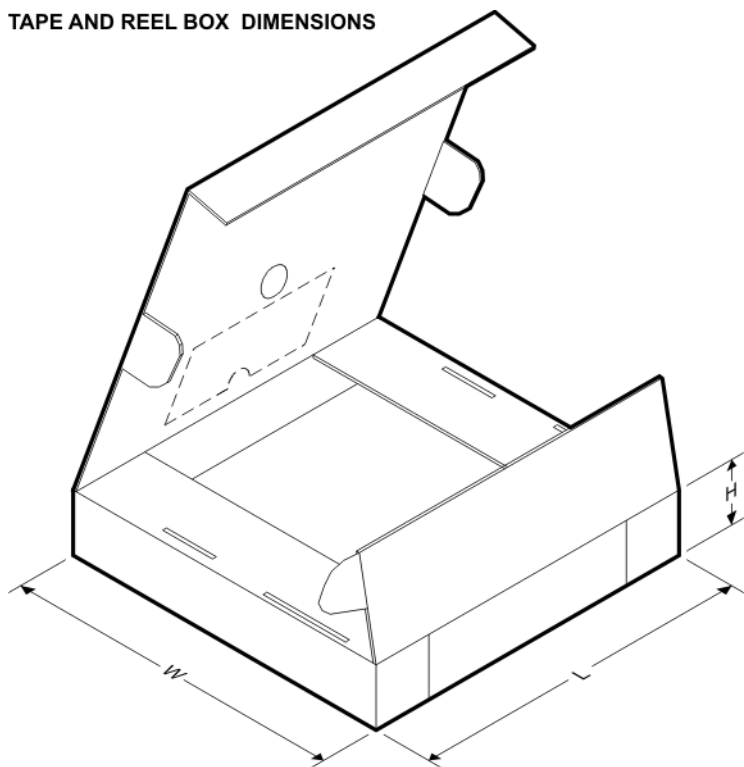
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC374DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AHC374DGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHC374DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AHC374NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AHC374PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



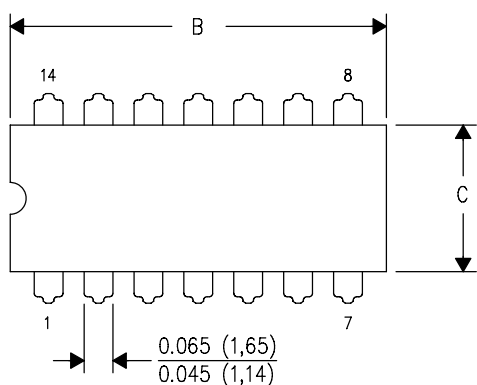
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC374DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74AHC374DGVR	TVSOP	DGV	20	2000	346.0	346.0	29.0
SN74AHC374DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74AHC374NSR	SO	NS	20	2000	346.0	346.0	41.0
SN74AHC374PWR	TSSOP	PW	20	2000	346.0	346.0	33.0

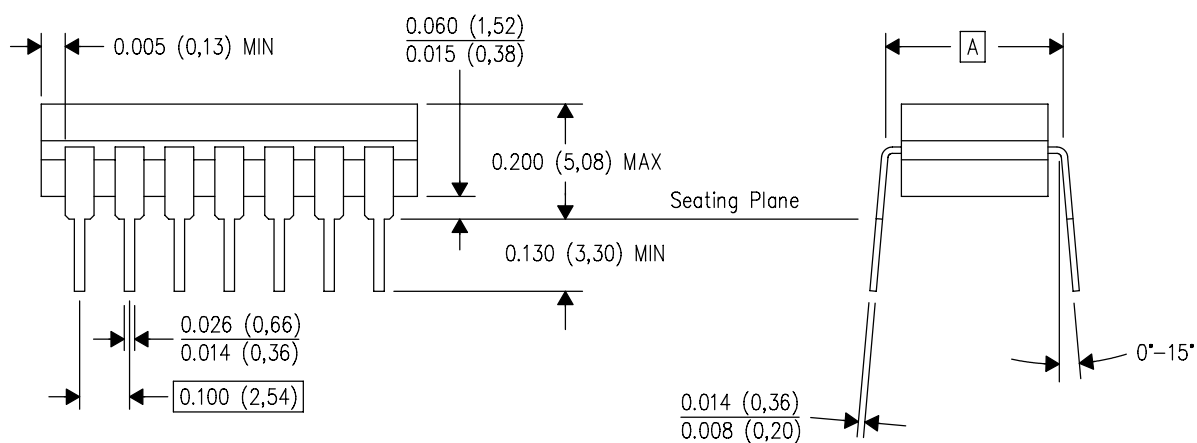
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

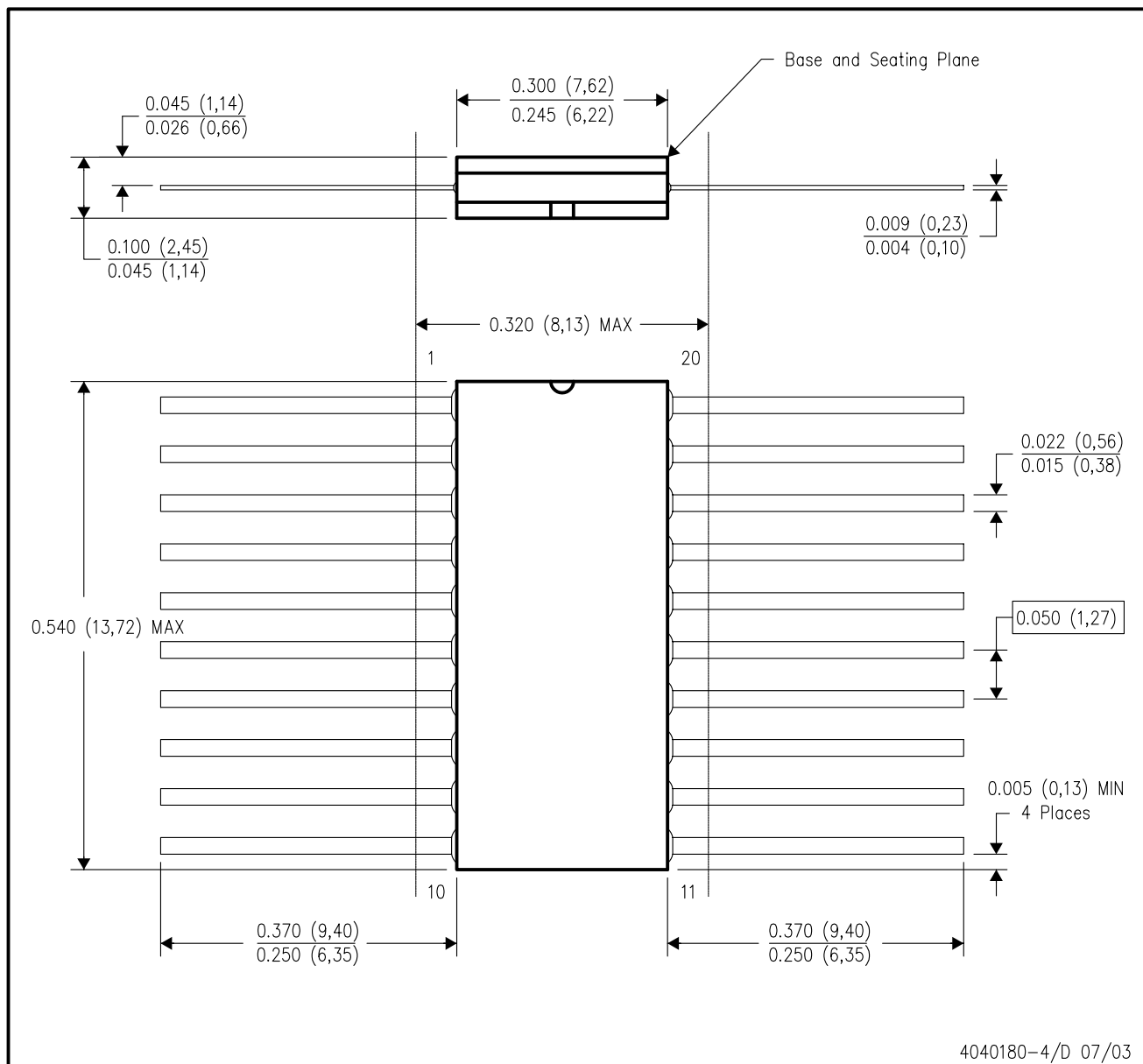


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

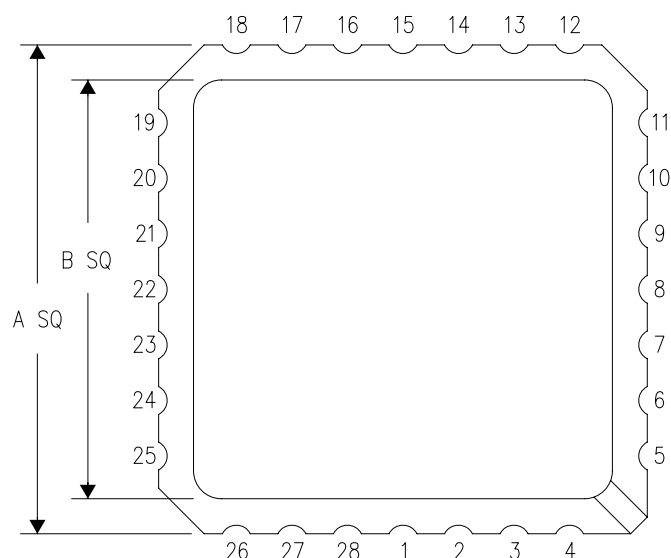


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

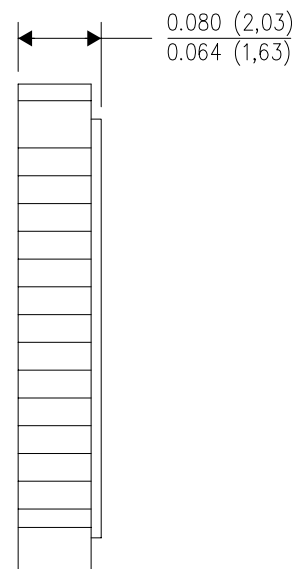
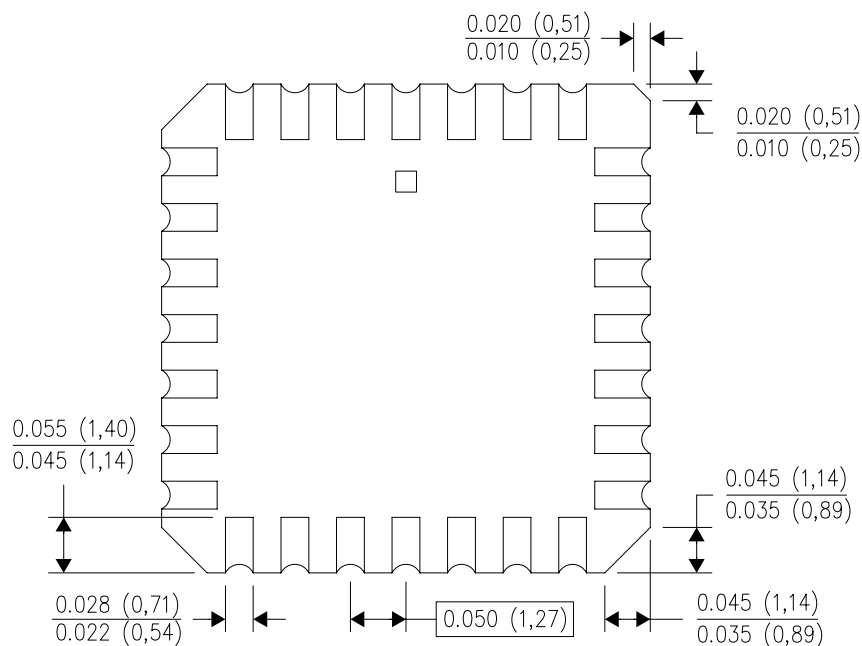
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



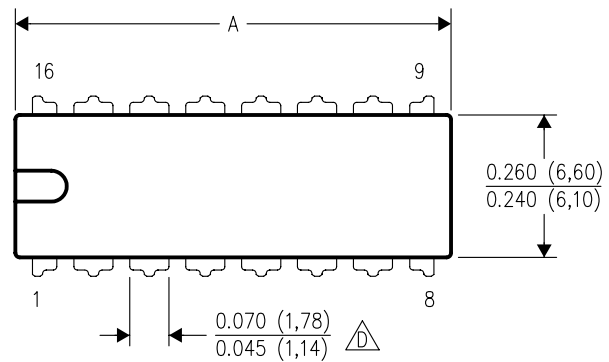
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

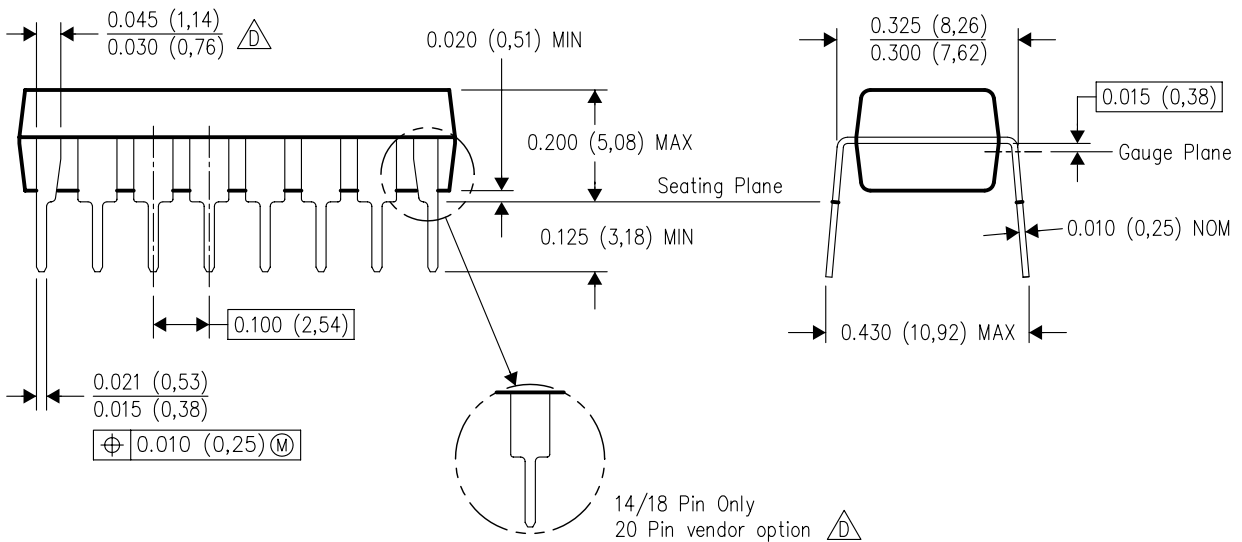
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only
20 Pin vendor option

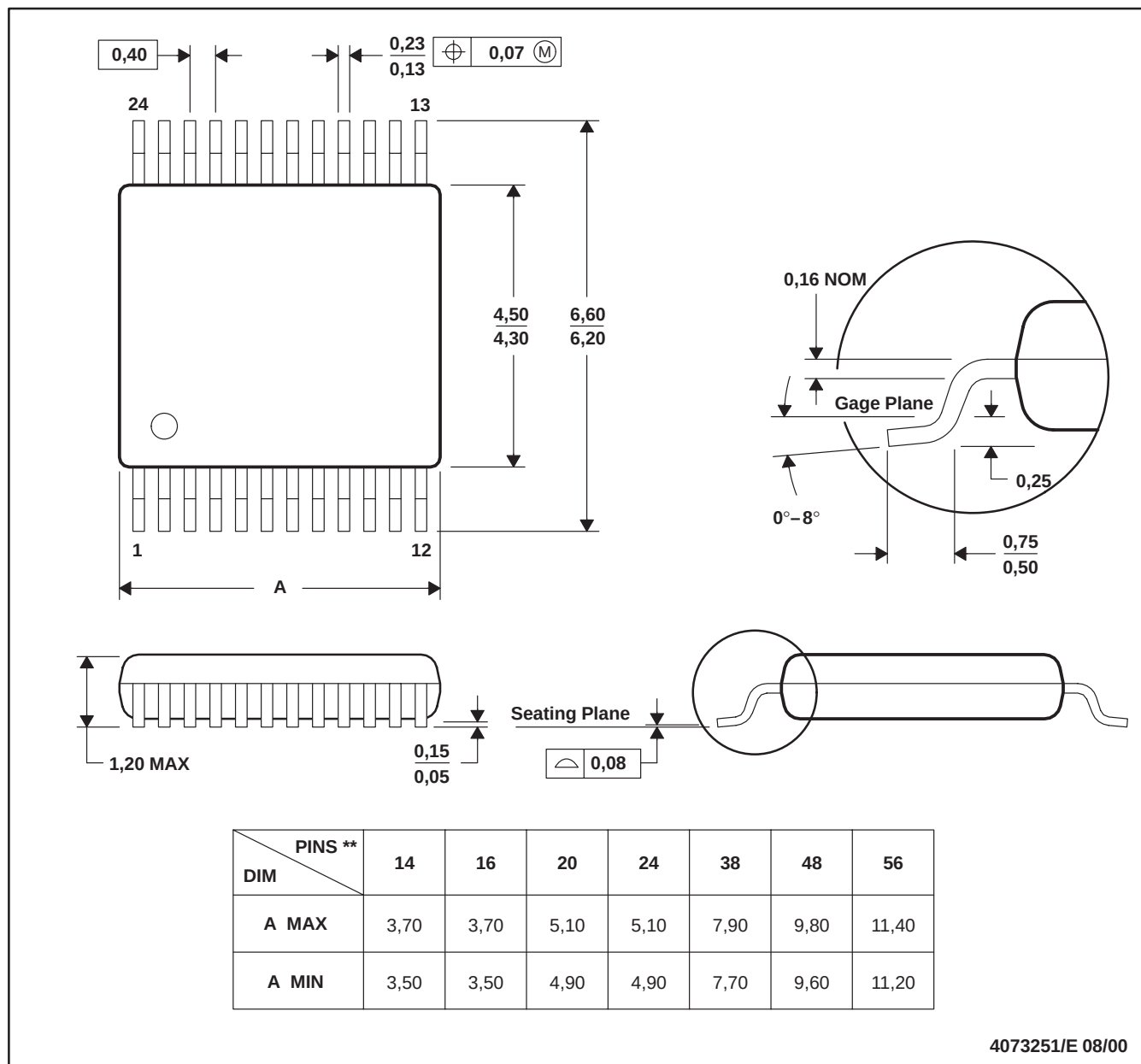
4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

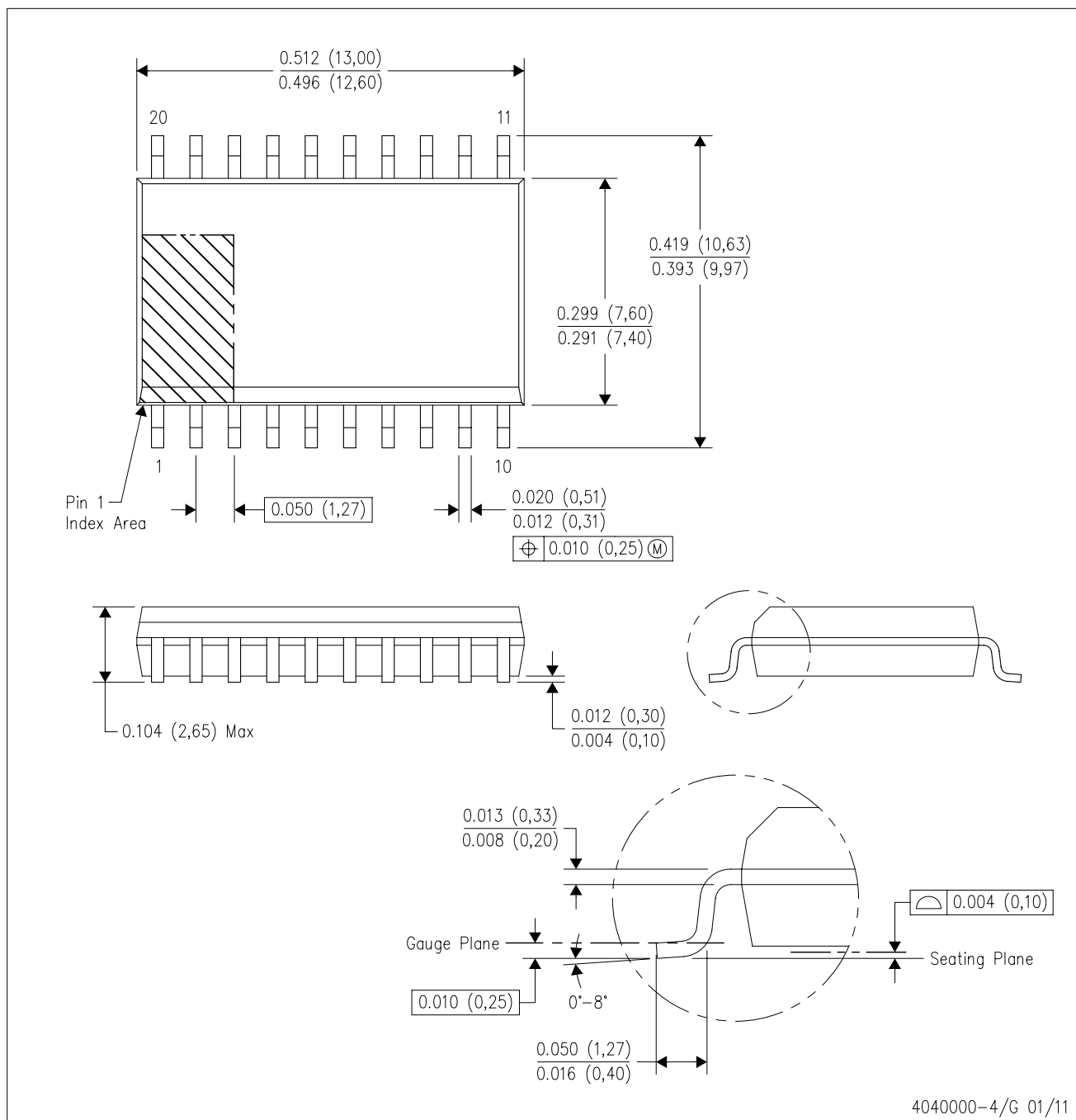
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G20)

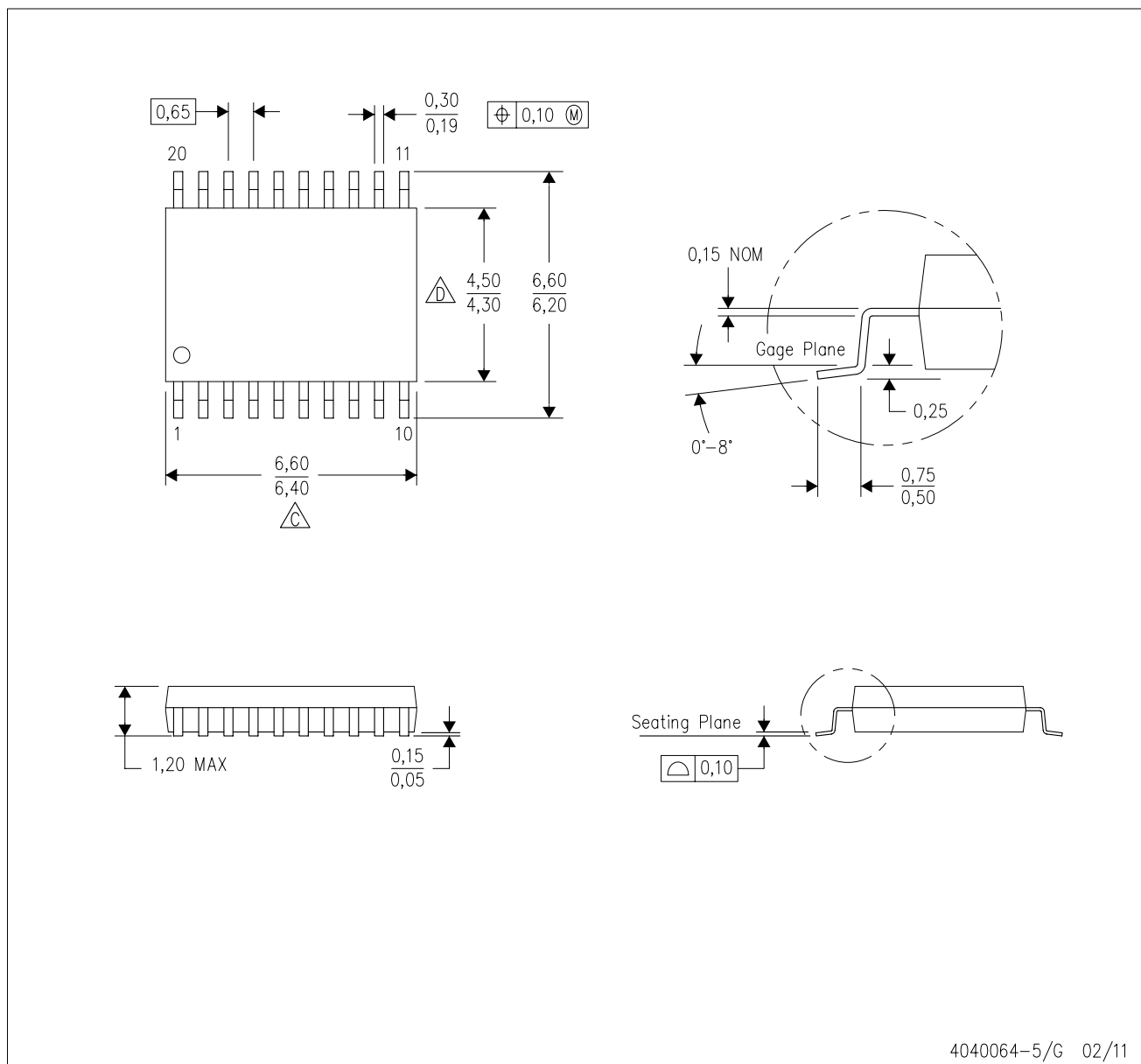
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



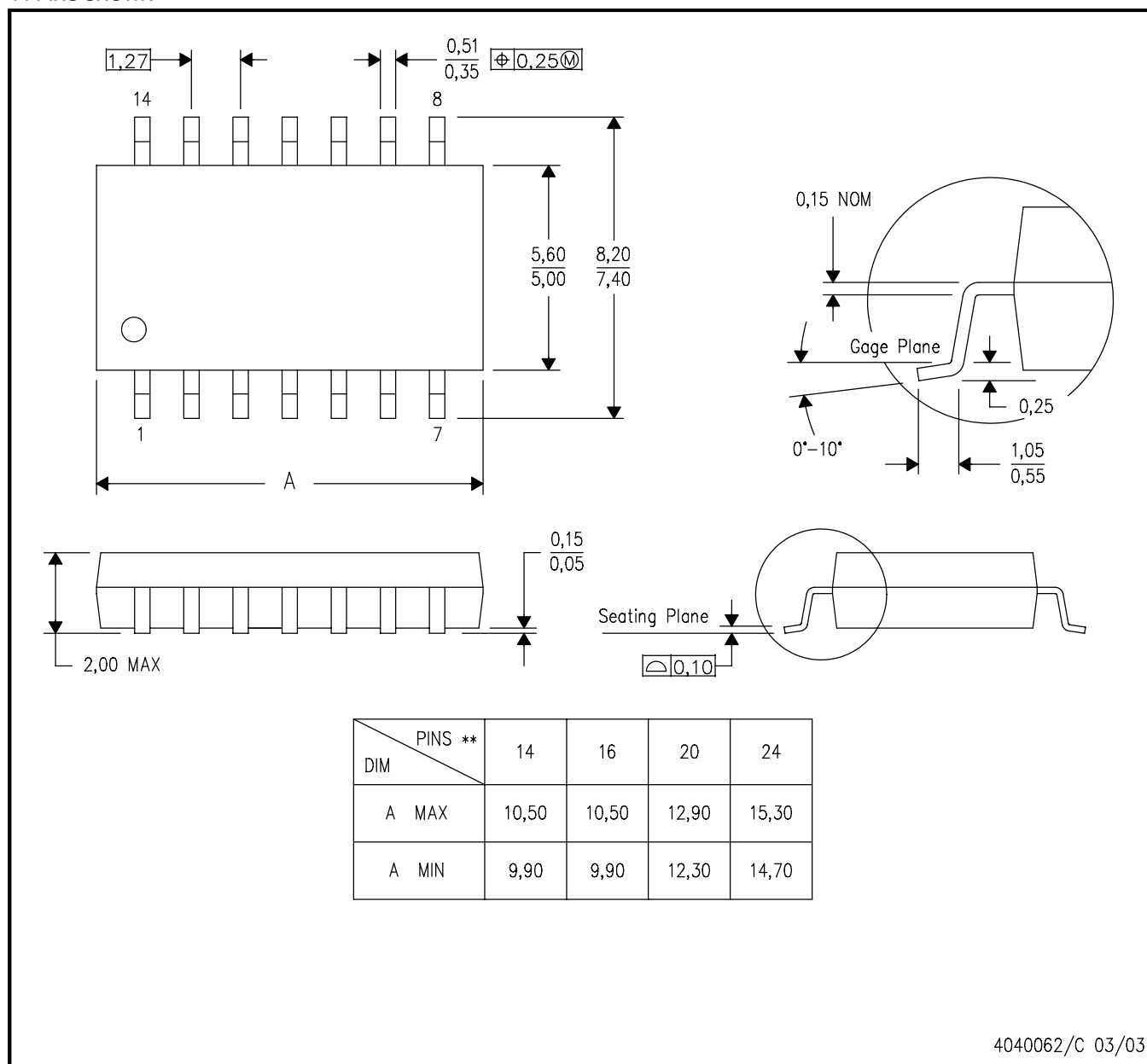
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

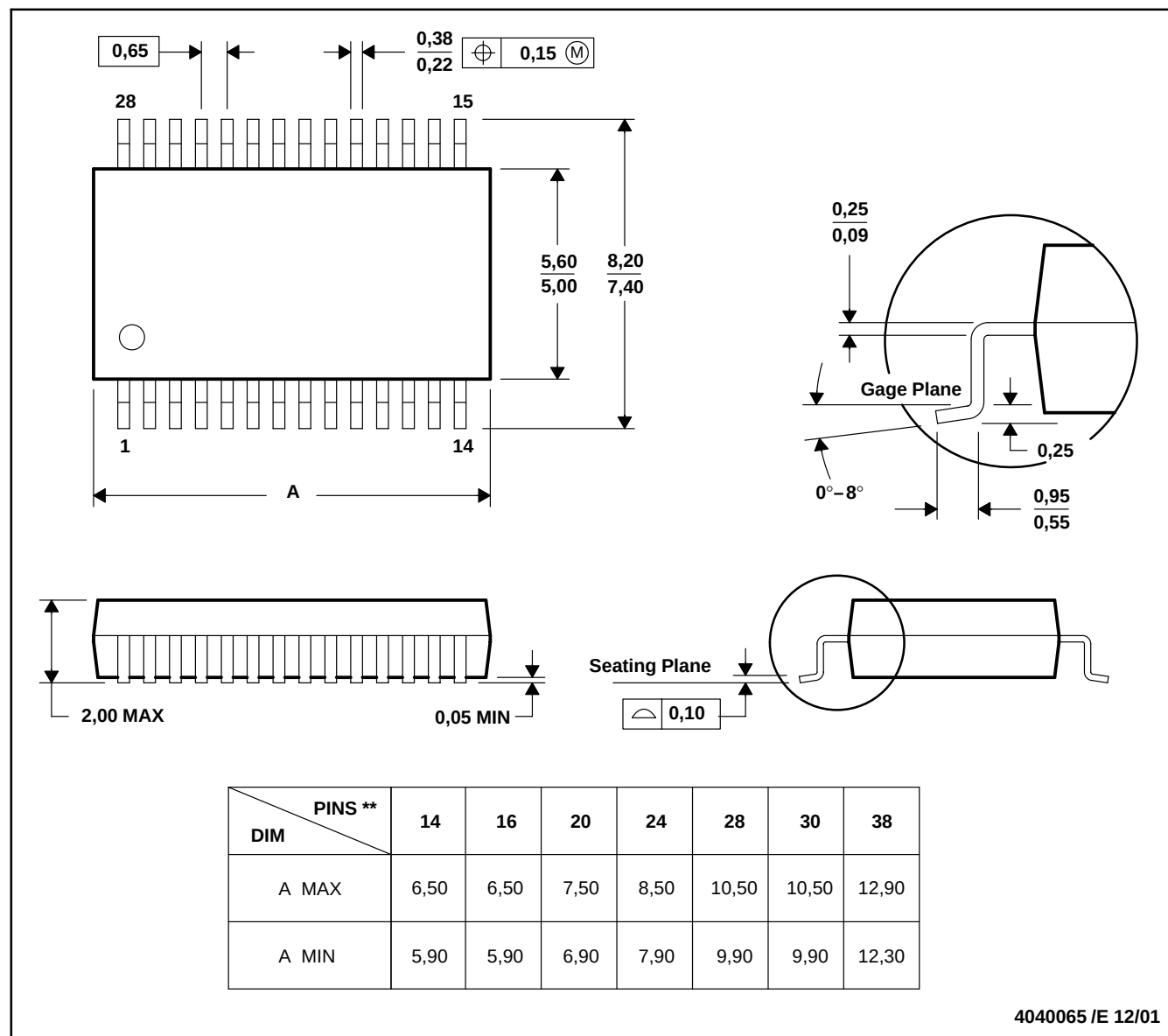


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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